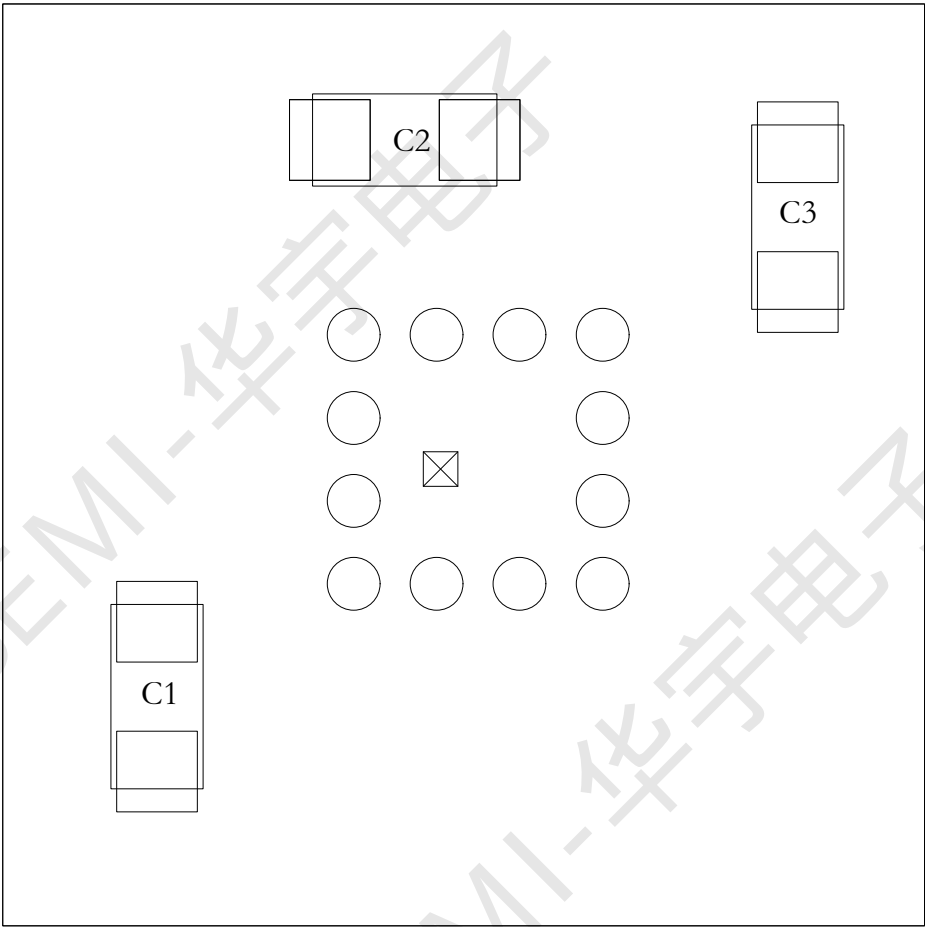
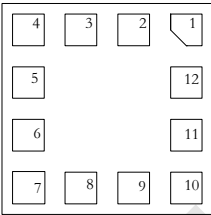


样品验证，禁止量产！

PIN 1

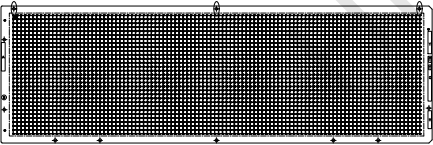


PIN 1



底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：上侧三个圆孔



实物图：
Chip photo:



特殊说明 Special Instructions：

SMT注意：
1.控制溢锡，防止沾锡。

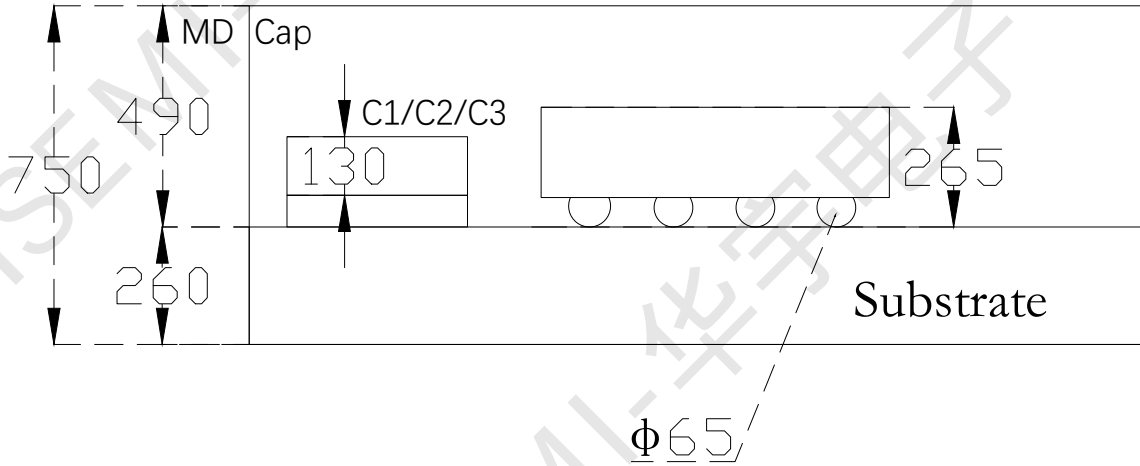
NO.	Item	Reference	value	size	package	KD P/N	Quantity
1	C1	C0105X5R104M100NTZ	0105 X5R 100nF +/-20% 10V	0.2*0.4*0.130mm	01005		1
2	C2/C3	C0105C0G101J500NTZ	0105 COG 100pF +/-5% 50V	0.2*0.4*0.130mm	01005		2
3	基板	substrate	基板	240X76.3X0.26mm	/	FCLGA12L(020020)576001	1
4	锡膏	/	F590 SnCu0.7-89M4		/		/
SMT元器件总计							3

拟制 Prepared by		制图日期 Create Date	2025/1/15	生效日期 Effective Date		客户确认签字/盖章： Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce incestimable loss. Thank you



工程验证，禁止量产！



拟制
Prepared by

制图日期
Create Date

2025/1/15

生效日期
Effective Date

客户确认签字/盖章:
Customer Signature

研发审核
R&d check

产品工程审核
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